

IN THE CLAIMS:

Please CANCEL without prejudice or disclaimer claims 1-9 in the underlying PCT application and ADD new claims 10-21 in accordance with the following:

Claims 1-9 (cancelled)

10. (new) A method, comprising:

connecting a circuit carrier to a component via contacts which place the component at a distance from the circuit carrier;

applying a foil to the component and the circuit carrier;

metallizing the foil; and

placing a solder bump as a contact element on a first side of the circuit carrier on which the component is arranged, the solder bump projecting beyond the component.

11. (new) A method according to claim 10, wherein said metallizing of the foil includes electrically strengthening metallization of the foil.

12. (new) A method according to claim 11, further comprising opening a window in the foil on a side of the component facing away from the circuit carrier.

13. (new) A method according to claim 12, wherein the component is a high-frequency component, especially an very-high frequency component.

14. (new) A method according to claim 13, further comprising mounting a passive component on the circuit carrier.

15. (new) A method according to claim 14, wherein said mounting of the passive component occurs on a second side opposite the first side of the circuit carrier on which the high-frequency component is connected.

16. (new) A high frequency package, manufactured in accordance with claim 10.

17. (new) A high frequency package, manufactured in accordance with claim 11.

18. (new) A high frequency package, manufactured in accordance with claim 12.

19. (new) A high frequency package, manufactured in accordance with claim 13.
20. (new) A high frequency package, manufactured in accordance with claim 14.
21. (new) A high frequency package, manufactured in accordance with claim 15.